

Day : Wednesday

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PALM INTRANET

Inventor Information for 10/621527

Inventor Name	City	State/Country
<u>ICHIROKU, NOBUHIRO</u>	USUI-GUN	JAPAN
<u>YOSHINO, MASACHIKA</u>	NISHIKAMO-GUN	JAPAN
<u>AKIBA, HIDEKI</u>	USUI-GUN	JAPAN
<u>SHIOBARA, TOSHIO</u>	USUI-GUN	JAPAN

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Inventor Name Search Result

Your Search was:

Last Name = ICHIROKU

First Name = NOBUHIRO

Application#	Patent#	Status	Date Filed	Title	Inventor Name 11
<u>10829150</u>	Not Issued	030	04/22/2004	DICING/DIE BONDING ADHESION TAPE	ICHIROKU, NOBUHIRO
<u>10713163</u>	Not Issued	020	11/17/2003	WAFER DICING/DIE BONDING SHEET	ICHIROKU, NOBUHIRO
<u>10621527</u> ✕	Not Issued	030	07/18/2003	PHENOLIC HYDROXYL-BEARING POLYIMIDE RESIN, MAKING METHOD AND POLYIMIDE RESIN COMPOSITION	ICHIROKU, NOBUHIRO
<u>10430309</u>	Not Issued	030	05/07/2003	HEAT RESISTANT RESIN COMPOSITION AND ADHESIVE FILM	ICHIROKU, NOBUHIRO
<u>10422011</u>	Not Issued	071	04/24/2003	CONDUCTIVE RESIN COMPOSITION	ICHIROKU, NOBUHIRO
<u>10366388</u>	Not Issued	094	02/14/2003	HEAT RESISTANT RESIN COMPOSITION AND ADHESIVE FILM	ICHIROKU, NOBUHIRO
<u>09898026</u>	<u>6506822</u>	150	07/05/2001	EPOXY RESIN COMPOSITION	ICHIROKU, NOBUHIRO
<u>09808186</u>	<u>6645632</u>	150	03/15/2001	FILM-TYPE ADHESIVE FOR ELECTRONIC COMPONENTS, AND ELECTRONIC COMPONENTS BONDED THEREWITH	ICHIROKU, NOBUHIRO
<u>09650724</u>	Not Issued	161	08/30/2000	FILM ADHESIVE AND ELECTRONIC PARTS BONDED THEREWITH	ICHIROKU, NOBUHIRO
<u>09234482</u>	<u>6117953</u>	150	01/21/1999	LIQUID EPOXY RESIN COMPOSITION FOR BALL GRID ARRAY PACKAGE	ICHIROKU, NOBUHIRO
<u>08399473</u>	<u>5473091</u>	150	03/07/1995	QUATERNARY PHOSPHORUS COMPOUNDS AND THEIR PREPARATION	ICHIROKU, NOBUHIRO

Inventor Search Completed: No Records to Display.

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ICHIROKU

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PALM INTRANET

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Inventor Name Search Result

Your Search was:

Last Name = YOSHINO

First Name = MASACHIKA

Application#	Patent#	Status	Date Filed	Title	Inventor Name 23
<u>10797139</u>	Not Issued	095	03/11/2004	LIGHT-EMITTING SEMICONDUCTOR POTTING COMPOSITION AND LIGHT-EMITTING SEMICONDUCTOR DEVICE	YOSHINO, MASACHIKA
<u>10737748</u>	Not Issued	020	12/18/2003	CONDUCTIVE ADHESIVE COMPOSITION	YOSHINO, MASACHIKA
<u>10713163</u>	Not Issued	020	11/17/2003	WAFER DICING/DIE BONDING SHEET	YOSHINO, MASACHIKA
<u>10621527</u>	Not Issued	030	07/18/2003	PHENOLIC HYDROXYL-BEARING POLYIMIDE RESIN, MAKING METHOD AND POLYIMIDE RESIN COMPOSITION	YOSHINO, MASACHIKA
<u>10422011</u>	Not Issued	071	04/24/2003	CONDUCTIVE RESIN COMPOSITION	YOSHINO, MASACHIKA
<u>10352129</u>	Not Issued	061	01/28/2003	SEMICONDUCTOR SEALING SILICONE COMPOSITION AND SEMICONDUCTOR DEVICE	YOSHINO, MASACHIKA
<u>09841046</u>	<u>6518332</u>	150	04/25/2001	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS, AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	YOSHINO, MASACHIKA
<u>09299880</u>	Not Issued	164	04/27/1999	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS, AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	YOSHINO, MASACHIKA
<u>09054448</u>	<u>6103026</u>	150	04/03/1998	CORROSION-RESISTANT COPPER MATERIALS AND	YOSHINO, MASACHIKA

				MAKING METHOD	
<u>08993403</u>	<u>6084037</u>	150	12/18/1997	EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	YOSHINO , MASACHIKA
<u>08420504</u>	<u>5519082</u>	150	04/12/1995	CURABLE SILICONE RUBBER COMPOSITION AND METHOD FOR PREPARING SILICONE RUBBER	YOSHINO , MASACHIKA
<u>08339665</u>	<u>5563203</u>	150	11/14/1994	SILICONE RUBBER COMPOSITIONS AND CURED PRODUCTS THEREOF	YOSHINO , MASACHIKA
<u>08205303</u>	Not Issued	161	03/03/1994	SILICONE RUBBER COMPOSITIONS AND CURED PRODUCTS THEREOF	YOSHINO , MASACHIKA
<u>08065269</u>	<u>5340872</u>	250	05/21/1993	SILICONE RUBBER COMPOSITIONS AND THEIR CURED PRODUCTS	YOSHINO , MASACHIKA
<u>08048577</u>	<u>5367001</u>	150	04/09/1993	IMPRESSION COMPOSITION	YOSHINO , MASACHIKA
<u>08004277</u>	Not Issued	161	01/14/1993	CURABLE SILICONE RUBBER COMPOSITIONS AND CURED PRODUCTS	YOSHINO , MASACHIKA
<u>07860485</u>	<u>5246982</u>	150	03/30/1992	SILICONE RUBBER COMPOSITION	YOSHINO , MASACHIKA
<u>07746367</u>	Not Issued	161	08/16/1991	CURABLE SILICONE RUBBER COMPOSITIONS AND CURED PRODUCTS	YOSHINO , MASACHIKA
<u>07698025</u>	<u>5179148</u>	150	05/10/1991	SILICONE RUBBER COMPOSITION AND METHOD FOR THE PREPARATION THEREOF	YOSHINO , MASACHIKA
<u>07501715</u>	Not Issued	166	03/30/1990	IMPRESSION COMPOSITION	YOSHINO , MASACHIKA
<u>07422206</u>	<u>5066714</u>	150	10/17/1989	CURABLE ORGANOPOLYSILOXANE PUTTY-LIKE COMPOSITION	YOSHINO , MASACHIKA
<u>07163434</u>	<u>4879339</u>	150	03/03/1988	STORAGE STABLE AND ROOM TEMPERATURE-CURABLE ORGANOPOLYSILOXANE COMPOSITION	YOSHINO , MASACHIKA
<u>06774802</u>	<u>4727168</u>	150	09/11/1985	ADHESION PROMOTOR	YOSHINO , MASACHIKA

Inventor Search Completed: No Records to Display.

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First Name

MASACHIKA

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PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = AKIBA

First Name = HIDEKI

Application#	Patent#	Status	Date Filed	Title	Inventor Name 3
<u>10713163</u>	Not Issued	020	11/17/2003	WAFER DICING/DIE BONDING SHEET	AKIBA, HIDEKI
<u>10621527</u>	Not Issued	030	07/18/2003	PHENOLIC HYDROXYL-BEARING POLYIMIDE RESIN, MAKING METHOD AND POLYIMIDE RESIN COMPOSITION	AKIBA, HIDEKI
<u>10422011</u>	Not Issued	071	04/24/2003	CONDUCTIVE RESIN COMPOSITION	AKIBA, HIDEKI

Inventor Search Completed: No Records to Display.**Search Another:
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 PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = SHIOBARA

First Name = TOSHIO

Application#	Patent#	Status	Date Filed	Title	Inventor Name 51
<u>10885678</u>	Not Issued	020	07/08/2004	METHOD FOR SEALING SEMICONDUCTOR COMPONENT	SHIOBARA, TOSHIO
<u>10885670</u>	Not Issued	020	07/08/2004	SILICONE RUBBER COMPOSITION, LIGHT-EMITTING SEMICONDUCTOR EMBEDDING/PROTECTING MATERIAL AND LIGHT-EMITTING SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10842492</u>	Not Issued	020	05/11/2004	LIQUID EPOXY RESIN COMPOSITION AND FLIP CHIP SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10829150</u>	Not Issued	030	04/22/2004	DICING/DIE BONDING ADHESION TAPE	SHIOBARA, TOSHIO
<u>10808329</u>	Not Issued	020	03/25/2004	LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10797139</u>	Not Issued	095	03/11/2004	LIGHT-EMITTING SEMICONDUCTOR POTTING COMPOSITION AND LIGHT-EMITTING SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10737748</u>	Not Issued	020	12/18/2003	CONDUCTIVE ADHESIVE COMPOSITION	SHIOBARA, TOSHIO
<u>10732519</u>	Not Issued	020	12/11/2003	RADIATION CURING SILICONE RUBBER COMPOSITION, ADHESIVE SILICONE ELASTOMER FILM FORMED FROM SAME, SEMICONDUCTOR DEVICE USING SAME, AND METHOD OF PRODUCING	SHIOBARA, TOSHIO

				SEMICONDUCTOR DEVICE	
<u>10713163</u>	Not Issued	020	11/17/2003	WAFER DICING/DIE BONDING SHEET	SHIOBARA, TOSHIO
<u>10659266</u>	Not Issued	030	09/11/2003	LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10638337</u>	Not Issued	030	08/12/2003	SEMICONDUCTOR ENCAPSULATING FLAME RETARDANT EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10422011</u>	Not Issued	071	04/24/2003	CONDUCTIVE RESIN COMPOSITION	SHIOBARA, TOSHIO
<u>10366388</u>	Not Issued	094	02/14/2003	HEAT RESISTANT RESIN COMPOSITION AND ADHESIVE FILM	SHIOBARA, TOSHIO
<u>10366357</u>	Not Issued	071	02/14/2003	RADIATION CURING SILICONE RUBBER COMPOSITION AND ADHESIVE SILICONE ELASTOMER FILM	SHIOBARA, TOSHIO
<u>10358188</u>	<u>6783859</u>	150	02/05/2003	SEMICONDUCTOR ENCAPSULATING FLAME RETARDANT EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10358187</u>	Not Issued	041	02/05/2003	OPTICAL WAVEGUIDE FORMING MATERIAL AND METHOD	SHIOBARA, TOSHIO
<u>10350110</u>	<u>6794058</u>	150	01/24/2003	FLIP-CHIP TYPE SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10327145</u>	<u>6780674</u>	150	12/24/2002	LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10235507</u>	<u>6680007</u>	150	09/06/2002	CONDUCTIVE RESIN COMPOSITIONS AND ELECTRONIC PARTS USING THE SAME	SHIOBARA, TOSHIO
<u>10218625</u>	<u>6733902</u>	150	08/15/2002	LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10196222</u>	<u>6723452</u>	150	07/17/2002	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10151099</u>	<u>6709756</u>	150	05/21/2002	OPTICAL DEVICE-RELATED ADHESIVE AND OPTICAL	SHIOBARA, TOSHIO

				DEVICE	
<u>10079495</u>	<u>6709753</u>	150	02/22/2002	SILICONE-MODIFIED EPOXY OR PHENOLIC RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES SEALED THEREWITH	SHIOBARA, TOSHIO
<u>09988752</u>	<u>6569532</u>	150	11/20/2001	EPOXY RESIN COMPOSITIONS AND PREMOLDED SEMICONDUCTOR PACKAGES	SHIOBARA, TOSHIO
<u>09987155</u>	Not Issued	092	11/13/2001	LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09955930</u>	<u>6558812</u>	150	09/20/2001	LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09950737</u>	<u>6627328</u>	150	09/13/2001	LIGHT-TRANSMISSIVE EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09949921</u>	Not Issued	161	09/12/2001	LIGHT-TRANSMISSIVE EPOXY RESIN COMPOSITION AND FLIP-CHIP TYPE SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09912400</u>	<u>6534193</u>	150	07/26/2001	LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09898026</u>	<u>6506822</u>	150	07/05/2001	EPOXY RESIN COMPOSITION	SHIOBARA, TOSHIO
<u>09883276</u>	Not Issued	094	06/19/2001	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09841046</u>	<u>6518332</u>	150	04/25/2001	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS, AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA, TOSHIO
<u>09808186</u>	<u>6645632</u>	150	03/15/2001	FILM-TYPE ADHESIVE FOR ELECTRONIC COMPONENTS, AND ELECTRONIC COMPONENTS BONDED THEREWITH	SHIOBARA, TOSHIO
<u>09774581</u>	<u>6479167</u>	150	02/01/2001	SEALING MATERIAL FOR FLIP-CHIP SEMICONDUCTOR DEVICE, AND FLIP-CHIP SEMICONDUCTOR DEVICE MADE THEREWITH	SHIOBARA, TOSHIO

<u>09726575</u>	<u>6399677</u>	150	12/01/2000	EPOXY RESIN COMPOSITIONS AND PREMOLDED SEMICONDUCTOR PACKAGES	SHIOBARA, TOSHIO
<u>09708682</u>	<u>6323263</u>	150	11/09/2000	SEMICONDUCTOR SEALING LIQUID EPOXY RESIN COMPOSITIONS	SHIOBARA, TOSHIO
<u>09650724</u>	Not Issued	161	08/30/2000	FILM ADHESIVE AND ELECTRONIC PARTS BONDED THEREWITH	SHIOBARA, TOSHIO
<u>09641817</u>	<u>6500564</u>	150	08/18/2000	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09640874</u>	<u>6342309</u>	150	08/18/2000	EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09590303</u>	<u>6376100</u>	150	06/09/2000	FLIP-CHIP TYPE SEMIDCONDUCTOR DEVICE UNDERFILL MATERIAL AND FLIP-CHIP TYPE SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09590081</u>	<u>6429238</u>	150	06/09/2000	FLIP-CHIP TYPE SEMICONDUCTOR DEVICE SEALING MATERIAL AND FLIP-CHIP TYPE SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09589279</u>	<u>6376923</u>	150	06/08/2000	SEALING MATERIAL FOR FILLING A GAP BETWEEN FLIP-CHIP TYPE SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09558384</u>	<u>6630745</u>	150	04/26/2000	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09550287</u>	<u>6512031</u>	150	04/14/2000	EPOXY RESIN COMPOSITION, LAMINATE FILM USING THE SAME, AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09548614</u>	<u>6383659</u>	150	04/13/2000	EPOXY RESIN COMPOSITION, LAMINATE FILM USING THE SAME, AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09534386</u>	<u>6291556</u>	150	03/24/2000	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO

<u>09527988</u>	<u>6372839</u>	150	03/17/2000	FLIP-CHIP TYPE SEMICONDUCTOR DEVICE UNDERFILL	SHIOBARA, TOSHIO
<u>09499382</u>	<u>6294271</u>	150	02/07/2000	FLIP-CHIP TYPE SEMICONDUCTOR DEVICE SEALING MATERIAL AND FLIP-CHIP TYPE SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09499038</u>	<u>6310120</u>	150	02/07/2000	FLIP-CHIP TYPE SEMICONDUCTOR DEVICE SEALING MATERIAL	SHIOBARA, TOSHIO
<u>09499022</u>	<u>6225704</u>	150	02/07/2000	FLIP-CHIP TYPE SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>09337520</u>	<u>6274251</u>	150	06/22/1999	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO

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Inventor Name Search Result

Your Search was:

Last Name = SHIOBARA

First Name = TOSHIO

Application#	Patent#	Status	Date Filed	Title	Inventor Name 51
<u>10621527</u>	Not Issued	030	07/18/2003	PHENOLIC HYDROXYL-BEARING POLYIMIDE RESIN, MAKING METHOD AND POLYIMIDE RESIN COMPOSITION	SHIOBARA, TOSHIO
<u>10620471</u>	Not Issued	030	07/17/2003	OPTICAL WAVEGUIDE, FORMING MATERIAL AND MAKING METHOD	SHIOBARA, TOSHIO
<u>10618765</u>	Not Issued	030	07/15/2003	LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10617827</u>	Not Issued	020	07/14/2003	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA, TOSHIO
<u>10430309</u>	Not Issued	030	05/07/2003	HEAT RESISTANT RESIN COMPOSITION AND ADHESIVE FILM	SHIOBARA, TOSHIO
<u>10422011</u>	Not Issued	071	04/24/2003	CONDUCTIVE RESIN COMPOSITION	SHIOBARA, TOSHIO
<u>09240575</u>	<u>6083774</u>	150	02/01/1999	METHOD OF FABRICATING A FLIP CHIP MOLD INJECTED PACKAGE	SHIOBARA , TOSHIO
<u>09234482</u>	<u>6117953</u>	150	01/21/1999	LIQUID EPOXY RESIN COMPOSITION FOR BALL GRID ARRAY PACKAGE	SHIOBARA , TOSHIO
<u>09189408</u>	<u>6160078</u>	150	11/10/1998	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHIOBARA , TOSHIO
<u>08993867</u>	<u>6001901</u>	150	12/18/1997	EPOXY RESIN COMPOSITION	SHIOBARA , TOSHIO
<u>08993403</u>	<u>6084037</u>	150	12/18/1997	EPOXY RESIN COMPOSITION	SHIOBARA ,

				AND SEMICONDUCTOR DEVICE	TOSHIO
<u>08919344</u>	<u>5935314</u>	150	08/28/1997	INORGANIC FILLER, EPOXY RESIN COMPOSITION, AND SEMICONDUCTOR DEVICE	SHIOBARA , TOSHIO
<u>08919242</u>	<u>5940688</u>	150	08/28/1997	EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>08688681</u>	Not Issued	161	07/29/1996	NAPHTHALENE AND/OR BIPHENYL SKELETON-CONTAINING EPOXY RESIN COMPOSITION	SHIOBARA , TOSHIO
<u>08187262</u>	<u>5418266</u>	150	01/27/1994	EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>08181953</u>	Not Issued	166	01/18/1994	EPOXY RESIN COMPOSITIONS AND CURED PRODUCTS	SHIOBARA , TOSHIO
<u>08181540</u>	<u>5358980</u>	150	01/14/1994	NAPHTHOL NOVOLAC EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>08014232</u>	Not Issued	161	02/05/1993	LIQUID EPOXY RESIN COMPOSITION AND CURED PRODUCT	SHIOBARA , TOSHIO
<u>07961000</u>	Not Issued	166	10/14/1992	EPOXY NOVOLAKS STABILISED WITH ORGANIC PHOSPHORUS COMPOUNDS	SHIOBARA , TOSHIO
<u>07955251</u>	Not Issued	161	10/01/1992	THERMOSETTING RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>07955136</u>	<u>5312878</u>	150	10/01/1992	A NAPHTHALENE CONTAINING EPOXY RESIN CURED WITH A DICYCLOPENTADIENE PHENOLIC RESIN	SHIOBARA , TOSHIO
<u>07928064</u>	<u>5290882</u>	150	08/11/1992	THERMOSETTING RESIN COMPOSITIONS	SHIOBARA , TOSHIO
<u>07921251</u>	<u>5306748</u>	150	07/29/1992	FLUORINE-MODIFIED THERMOSETTING RESIN AND THERMOSETTING RESIN COMPOSITION	SHIOBARA , TOSHIO

<u>07894480</u>	Not Issued	161	06/05/1992	THERMOSETTING RESIN COMPOSITIONS	SHIOBARA , TOSHIO
<u>07889369</u>	<u>5248710</u>	150	05/28/1992	FLIP CHIP ENCAPSULATING COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>07888712</u>	<u>5256720</u>	150	05/27/1992	POLYPROPYLENE RESIN COMPOSITION	SHIOBARA , TOSHIO
<u>07885965</u>	<u>5298548</u>	150	05/20/1992	EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>07863271</u>	<u>5300588</u>	150	04/03/1992	THERMOSETTING RESIN COMPOSITIONS	SHIOBARA , TOSHIO
<u>07858474</u>	Not Issued	161	03/27/1992	EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>07858458</u>	Not Issued	166	03/27/1992	EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>07856767</u>	<u>5362775</u>	150	03/24/1992	EPOXY RESIN COMPOSITION AND CURED PRODUCT THEREOF	SHIOBARA , TOSHIO
<u>07825222</u>	<u>5171869</u>	150	01/24/1992	ALLYL OR PROPENYL GROUP-CONTAINING NAPHTHALENE DERIVATIVES	SHIOBARA , TOSHIO
<u>07824967</u>	<u>5243058</u>	150	01/24/1992	ALLYL OR PROPENYL GROUP-CONTAINING NAPHTHALENE DERIVATIVES	SHIOBARA , TOSHIO
<u>07823477</u>	Not Issued	161	01/22/1992	SILICONE RUBBER COMPOSITIONS FOR USE IN THE PROTECTIVE COATING OF ELECTRONIC AND ELECTRIC PARTS	SHIOBARA , TOSHIO
<u>07820122</u>	Not Issued	161	01/14/1992	LIGHT TRANSMISSIVE EPOXY RESIN COMPOSITION AND OPTICAL SEMICONDUCTOR DEVICES	SHIOBARA , TOSHIO
<u>07803560</u>	Not Issued	161	12/09/1991	"EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICES ENCAPSULATED	SHIOBARA , TOSHIO

				THEREWITH"	
<u>07713841</u>	<u>5162400</u>	150	06/12/1991	EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHIOBARA , TOSHIO
<u>07681429</u>	Not Issued	161	04/05/1991	EPOXY RESIN COMPOSITION	SHIOBARA , TOSHIO
<u>07580668</u>	<u>5182351</u>	150	09/11/1990	THERMOSETTING RESIN COMPOSITIONS	SHIOBARA , TOSHIO
<u>07580647</u>	<u>5070154</u>	150	09/11/1990	COMPOSITION OF MALEIMIDE AND AROMATIC-DOUBLE BOND EPOXY RESIN	SHIOBARA , TOSHIO
<u>07523814</u>	<u>5173544</u>	150	05/16/1990	EPOXY RESIN COMPOSITIONS	SHIOBARA , TOSHIO
<u>07397739</u>	<u>5053445</u>	150	08/23/1989	EPOXY RESIN COMPOSITION	SHIOBARA , TOSHIO
<u>07328244</u>	Not Issued	166	03/24/1989	EPOXY RESIN COMPOSITION	SHIOBARA , TOSHIO
<u>07014540</u>	Not Issued	161	02/13/1987	EPOXY RESIN COMPOSITION	SHIOBARA , TOSHIO
<u>06928654</u>	<u>4902732</u>	150	11/05/1986	EPOXY RESIN-BASED CURABLE COMPOSITIONS	SHIOBARA , TOSHIO
<u>06916934</u>	Not Issued	161	10/07/1986	EPOXY RESIN COMPOSITION	SHIOBARA , TOSHIO
<u>06865416</u>	<u>4701482</u>	150	05/21/1986	EPOXY RESIN COMPOSITION FOR ENCAPSULATION OF SEMICONDUCTOR DEVICES	SHIOBARA , TOSHIO
<u>06865390</u>	<u>4701479</u>	150	05/21/1986	EPOXY RESIN-BASED COMPOSITION FOR ENCAPSULATION OF SEMICONDUCTOR DEVICES	SHIOBARA , TOSHIO
<u>06781533</u>	Not Issued	166	09/30/1985	EPOXY RESIN-BASED CURABLE COMPOSITIONS	SHIOBARA , TOSHIO
<u>06606703</u>	Not Issued	168	05/03/1984	EPOXY RESIN-BASED CURABLE COMPOSITIONS	SHIOBARA , TOSHIO
<u>06466040</u>	Not Issued	161	02/14/1983	POLYMERIC COMPOSITIONS FOR COATING OR ENCAPSULATING ELECTRONIC PARTS	SHIOBARA , TOSHIO

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Application#	Patent#	Status	Date Filed	Title	Inv Nam
<u>09404301</u>	<u>6210811</u>	150	09/24/1999	EPOXY RESIN COMPOSITION, LAMINATE FILM USING THE SAME, AND SEMICONDUCTOR DEVICE	SHI , TO
<u>09358481</u>	<u>6231997</u>	150	07/21/1999	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS, AND SEMICONDUCTOR DEVICES	SHI , TO
<u>09345390</u>	<u>6235865</u>	150	06/30/1999	PHOSPHONIUM BORATE COMPOUND, MAKING METHOD, CURING CATALYST, AND EPOXY RESIN COMPOSITION	SHI , TO
<u>09326588</u>	<u>6207296</u>	150	06/07/1999	INORGANIC FILLER, EPOXY RESIN COMPOSITION, AND SEMICONDUCTOR DEVICE	SHI , TO
<u>09310999</u>	<u>6162878</u>	150	05/13/1999	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHI , TO
<u>09310924</u>	<u>6297306</u>	150	05/13/1999	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHI , TO
<u>09305453</u>	<u>5994785</u>	150	05/06/1999	EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>09299880</u>	Not Issued	164	04/27/1999	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS, AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>09291285</u>	<u>6221509</u>	150	04/14/1999	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS, AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>09223373</u>	<u>6139978</u>	150	12/30/1998	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS, AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>09220439</u>	<u>6168872</u>	150	12/24/1998	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHI , TO

<u>09055301</u>	<u>6143423</u>	150	04/06/1998	FLAME RETARDANT EPOXY RESIN COMPOSITIONS	SHI , TO
<u>09054448</u>	<u>6103026</u>	150	04/03/1998	CORROSION-RESISTANT COPPER MATERIALS AND MAKING METHOD	SHI , TO
<u>09006868</u>	<u>6027812</u>	150	01/14/1998	ENCAPSULANT OF CRYSTALLINE EPOXY RESIN AND PHENOLIC RESIN-CRYSTALLINE EPOXY RESIN REACTION PRODUCT	SHI , TO
<u>09003517</u>	<u>6177489</u>	150	01/06/1998	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE	SHI , TO
<u>08993867</u>	<u>6001901</u>	150	12/18/1997	EPOXY RESIN COMPOSITION	SHI , TO
<u>08940963</u>	Not Issued	161	09/30/1997	EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE ENCAPSULATED THEREWITH	SHI , TO
<u>08796544</u>	<u>5827908</u>	150	02/06/1997	NAPHTHALENE AND OR BIPHENYL SKELETON CONTAINING EPOXY RESIN COMPOSITION	SHI , TO
<u>08735504</u>	<u>5700853</u>	150	10/23/1996	SILICONE RUBBER COMPOSITIONS	SHI , TO
<u>08615145</u>	<u>5739187</u>	150	03/14/1996	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>08566263</u>	<u>5731370</u>	150	12/01/1995	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS WITH 2-PHENYL-4,5-DIHYDROXYMETHYLMIDAZOLE CURING ACCELERATOR	SHI , TO
<u>08413929</u>	<u>5643975</u>	150	03/30/1995	EPOXY RESIN COMPOSITIONS AND CURED PRODUCTS	SHI , TO
<u>08399473</u>	<u>5473091</u>	150	03/07/1995	QUATERNARY PHOSPHORUS COMPOUNDS AND THEIR PREPARATION	SHI , TO
<u>08377247</u>	Not Issued	166	01/24/1995	EPOXY RESIN COMPOSITIONS	SHI , TO
<u>08216566</u>	<u>5362887</u>	150	03/23/1994	FLUORINE - MODIFIED ACID ANHYDRIDES	SHI , TO
<u>08160912</u>	<u>5336786</u>	150	12/03/1993	ORGANIC SILICON COMPOUNDS	SHI , TO
<u>08103832</u>	Not Issued	163	08/09/1993	EPOXY NOVOLAKS STABILISED WITH ORGANIC PHOSPHORUS COMPOUNDS	SHI , TO
<u>08085818</u>	Not Issued	161	07/06/1993	EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>08017290</u>	<u>5340851</u>	150	02/12/1993	THERMOSETTING RESIN COMPOSITIONS	SHI , TO
<u>08013409</u>	<u>5326589</u>	150	02/04/1993	METHOD OF PROTECTING ELECTRONIC OR ELECTRIC PART	SHI , TO

<u>07981209</u>	<u>5250637</u>	150	11/25/1992	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES	SHI , TO
<u>07798750</u>	<u>5225484</u>	150	11/27/1991	EPOXY RESIN COMPOSITIONS AND CURED PRODUCTS THEREOF	SHI , TO
<u>07785263</u>	Not Issued	161	10/30/1991	EPOXY RESIN COMPOSITIONS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>07779166</u>	<u>5235005</u>	150	10/21/1991	POLYIMIDE RESIN COMPOSITION AND SEMICONDUCTOR DEVICE ENCAPSULATED THEREWITH	SHI , TO
<u>07749379</u>	<u>5198479</u>	150	08/23/1991	LIGHT TRANSMISSIVE EPOXY RESIN COMPOSITIONS AND OPTICAL SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>07739447</u>	<u>5166228</u>	150	08/02/1991	EPOXY RESIN COMPOSITIONS CONTAINING POLYSUBSTITUTED NOVOLAC EPOXY RESINS AND NAPHTHYLENE BASED PHENOLIC RESIN CURING AGENTS AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH	SHI , TO
<u>07695012</u>	Not Issued	166	05/03/1991	EPOXY RESIN COMPOSITIONS AND CURED PRODUCTS	SHI , TO
<u>07651438</u>	<u>5175199</u>	150	02/07/1991	HIGH TRANSPARENCY SILICA-TITANIA GLASS BEADS, METHOD FOR MAKING, AND LIGHT TRANSMISSION EPOXY RESIN COMPOSITIONS	SHI , TO
<u>07649027</u>	<u>5179176</u>	150	02/01/1991	PROPENYL GROUP-CONTAINING EPOXY RESIN	SHI , TO
<u>07645498</u>	<u>5190995</u>	150	01/24/1991	NAPHTHALENE RING CONTAINING EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE ENCAPSULATED THEREWITH	SHI , TO
<u>07476700</u>	<u>5137940</u>	150	02/08/1990	SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS	SHI , TO
<u>07404600</u>	<u>4985751</u>	250	09/08/1989	RESIN-ENCAPSULATED SEMICONDUCTOR DEVICES	SHI , TO
<u>07373286</u>	<u>5006614</u>	150	06/29/1989	EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE ENCAPSULATED THEREWITH CONTAINING POLYMALEIMIDE AND (ALLYL-EPOXY) NOVOLAC/ SILOXANE GRAFT COPOLYMER	SHI , TO
<u>07373192</u>	Not Issued	166	06/29/1989	POLYIMIDE RESIN COMPOSITION AND SEMICONDUCTOR DEVICE ENCAPSULATED THEREWITH	SHI , TO
<u>07201439</u>	<u>4876298</u>	250	06/02/1988	EPOXY RESIN COMPOSITION	SHI , TO
<u>07179538</u>	<u>4877822</u>	150	04/08/1988	EPOXY RESIN COMPOSITION	SHI , TO

<u>07173624</u>	Not Issued	161	03/25/1988	EPOXY RESIN COMPOSITION	SHI , TO
<u>07168943</u>	<u>4859722</u>	150	03/16/1988	EPOXY RESIN COMPOSITION	SHI , TO
<u>06404890</u>	Not Issued	161	08/03/1982	EPOXY RESIN-BASED CURABLE COMPOSITIONS	SHI , TO

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